

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00354	1.66	0.05976
	Doped silicon	Silicon (Si)	7440-21-3	0.20995	98.34	3.54024
Subtotal				0.21349	100	3.6
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.00697	5.0	0.11761
	Silver alloy	Silver (Ag)	7440-22-4	0.00209	1.5	0.03528
	Lead alloy	Lead (Pb)	7439-92-1	0.13043	93.5	2.19934
Subtotal				0.13949	100	2.35223
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11862	100.0	2.00024
Subtotal				0.11862	100	2.00024
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.06535	0.1	1.102
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01961	0.03	0.3306
	Copper alloy	Copper (Cu)	7440-50-8	65.26822	99.87	1100.5674
Subtotal				65.35318	100	1102
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.13462	100.0	2.27
Subtotal				0.13462	100	2.27
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.53183	4.5	25.83
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.40406	10.0	57.4
	Filler	Silica fused	60676-86-0	25.53044	75.0	430.5
	Metal hydroxide	Metal hydroxide		3.40406	10.0	57.4
	Carbon Black	Carbon black	1333-86-4	0.1702	0.5	2.87
Subtotal				34.04059	100	574
Total				99.99999	100	1686.22247

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